PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5293810

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the TYPOGRAPHICAL ERROR IN THE 3RD INVENTOR'S NAME previously recorded on Reel 037929 Frame 0313. Assignor(s) hereby confirms the ASSIGNMENT OF ASSIGNOR'S INTEREST.
RESUBMIT DOCUMENT ID:	505120422

CONVEYING PARTY DATA

Name	Execution Date
CHUEI-TANG WANG	08/22/2018
WEI-TING CHEN	08/21/2018
CHIEH-YEN CHEN	08/21/2018
HAO-YI TSAI	08/21/2018
MING HUNG TSENG	08/21/2018
HUNG-YI KUO	08/21/2018
CHEN-HUA YU	08/22/2018

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	8, Li-Hsin Rd. 6, Hsinchu Science Park
City:	HsinChu
State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15061419

CORRESPONDENCE DATA

Fax Number: (972)732-9218

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 972-732-1001
Email: docketing@slatermatsil.com
Correspondent Name: SLATER MATSIL, LLP
Address Line 1: 17950 PRESTON RD., SUITE 1000
Address Line 4: DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TSMP20151292US00

NAME OF SUBMITTER:	MARANDA BRALLEY
SIGNATURE:	/Maranda Bralley/
DATE SIGNED:	12/20/2018

Total Attachments: 8

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source=TSMP20151292US00 Notice of Recordation of Assignment sent 2016-03-16#page5.tif
source=TSMP20151292US00 Notice of Recordation of Assignment sent 2016-03-16#page6.tif
source=TSMP20151292US00 Corrective Assignment#page1.tif
source=TSMP20151292US00 Corrective Assignment#page2.tif

UNITED STATES PATENT AND TRADEMARK OFFICE
UNDER SECRETARY OF COMMERCE FOR INTELLECTUAL PROPERTY AND
DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE

MARCH 10, 2016

PTAS

SLATER & MATSIL, LLP
17950 PRESTON RD.
SUITE 1000
DALLAS, TX 75252

503728218

UNITED STATES PATENT AND TRADEMARK OFFICE
NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT

THE ENCLOSED DOCUMENT HAS BEEN RECORDED BY THE ASSIGNMENT RECORDATION BRANCH OF THE U.S. PATENT AND TRADEMARK OFFICE. A COMPLETE COPY IS AVAILABLE AT THE ASSIGNMENT SEARCH ROOM ON THE REEL AND FRAME NUMBER REFERENCED BELOW.

PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY CONTACT THE ASSIGNMENT RECORDATION BRANCH AT 571-272-3350. PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE, MAIL STOP: ASSIGNMENT RECORDATION BRANCH, P.O. BOX 1450, ALEXANDRIA, VA 22313.

RECORDATION DATE: 03/09/2016 REEL/FRAME: 037929/0313
NUMBER OF PAGES: 4

BRIEF: ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS).

DOCKET NUMBER: TSMP20151292US00

ASSIGNOR:
WANG, CHUEI-TANG DOC DATE: 02/26/2016

ASSIGNOR:
CHEN, WEI-TING DOC DATE: 02/26/2016

ASSIGNOR:
CHEN, VINCENT DOC DATE: 02/26/2016

ASSIGNOR:
TSAI, HAO-YI DOC DATE: 02/26/2016

ASSIGNOR:
TSENG, MING HUNG DOC DATE: 02/26/2016

ASSIGNOR:
KUO, HUNG-YI DOC DATE: 02/26/2016

ASSIGNOR:
YU, CHEN-HUA DOC DATE: 02/26/2016

ASSIGNEE:
TAIWAN SEMICONDUCTOR MANUFACTURING
COMPANY, LTD.
NO. 8, LI-HSIN RD. 6
SCIENCE-BASED INDUSTRIAL PARK
HSIN-CHU, TAIWAN 300-77

APPLICATION NUMBER: 15061419 FILING DATE:
PATENT NUMBER: ISSUE DATE:
TITLE: INFO COIL ON METAL PLATE WITH SLOT

ASSIGNMENT RECORDATION BRANCH
PUBLIC RECORDS DIVISION

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHUEI-TANG WANG	02/26/2016
WEI-TING CHEN	02/26/2016
VINCENT CHEN	02/26/2016
HAO-YI TSAI	02/26/2016
MING HUNG TSENG	02/26/2016
HUNG-YI KUO	02/26/2016
CHEN-HUA YU	02/26/2016

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15061419

CORRESPONDENCE DATA

Fax Number:	(972)732-9218
Phone:	972-732-1001
Email:	docketing@slater-matsil.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name:	SLATER & MATSIL, LLP
Address Line 1:	17950 PRESTON RD.
Address Line 2:	SUITE 1000
Address Line 4:	DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TSMP20151292US00

NAME OF SUBMITTER:	WENDY SAXBY
Signature:	/Wendy Saxby/
Date:	03/09/2016

Total Attachments: 2
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RECEIPT INFORMATION

EPAS ID:	PAT3774861
Receipt Date:	03/09/2016

ATTORNEY DOCKET NO.
TSMP20151292US00

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77 Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	InFO Coil on Metal Plate with Slot			
SIGNATURE OF INVENTOR AND NAME	Chuei-Tang Wang Chuei-Tang Wang	WeiTing Chen Wei-Ting Chen	Vincent Chen Vincent Chen	Hao-Yi Tsai Hao-Yi Tsai
DATE	2016.02.26	2016.02.26	2016.2.26.	2016.2.26
RESIDENCE	Taichung City, Taiwan	Tainan City, Taiwan	Taipei City, Taiwan	Hsin-Chu, Taiwan

ATTORNEY DOCKET NO.
TSMP20151292US00

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77 Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	InFO Coil on Metal Plate with Slot			
SIGNATURE OF INVENTOR AND NAME	Ming Hung Tseng Ming Hung Tseng	Hung-yi Kuo Hung-Yi Kuo	Chen-Hua Yu	
DATE	2016, 2.26.	2/26'16	2/26/'16	
RESIDENCE	Toufen Township, Taiwan	Taipei City, Taiwan	Hsin-Chu, Taiwan	

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ATTORNEY DOCKET NO.
TSMP20151292US00

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77 Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year:

TITLE OF INVENTION	InFO Coil on Metal Plate with Slot			
SIGNATURE OF INVENTOR AND NAME	Chuei-Tang Wang Chuei-Tang Wang	Weiting Chen Wei-Ting Chen	Chieh-Yen Chen Chieh-Yen Chen	Hao-Yi Tsai Hao-Yi Tsai
DATE	8/22/2018	08/21/2018	08/21/2018	2018. 8. 21
RESIDENCE	Taichung City, Taiwan	Tainan City, Taiwan	Taipei City, Taiwan	Hsinchu, Taiwan

ATTORNEY DOCKET NO.
TSMP20151292US00

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77 Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year:

TITLE OF INVENTION	InFO Coil on Metal Plate with Slot			
SIGNATURE OF INVENTOR AND NAME	Ming Hung Tseng Ming Hung Tseng	Hung-Yi Kuo Hung-Yi Kuo	Chen-Hua Yu	
DATE	2018. 8. 21	8/24 '18	8/27/'18	
RESIDENCE	Toufen Township, Taiwan	Taipei City, Taiwan	Hsinchu, Taiwan	